

MA6X125 (MA125)

Silicon epitaxial planar type

For switching circuit

■ Features

- Four isolated elements contained in one package, allowing high-density mounting

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	40	V
Maximum peak reverse voltage	V_{RM}	40	V
Forward current *	I_F	100	mA
Peak forward current *	I_{FM}	200	mA
Junction temperature	T_j	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +150	$^\circ\text{C}$

Note) *: Value for single diode

■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_F	$I_F = 100 \text{ mA}$			1.2	V
Reverse voltage	V_R	$I_R = 100 \mu\text{A}$	40			V
Reverse current	I_R	$V_R = 40 \text{ V}$			100	nA
Terminal capacitance	C_t	$V_R = 0 \text{ V}, f = 1 \text{ MHz}$			5.0	pF
Reverse recovery time *3	t_{rr1}^{*1}	$I_F = 10 \text{ mA}, V_R = 6 \text{ V}$		150		ns
	t_{rr2}^{*2}	$I_{rr} = 0.1 I_R, R_L = 100 \Omega$		9		

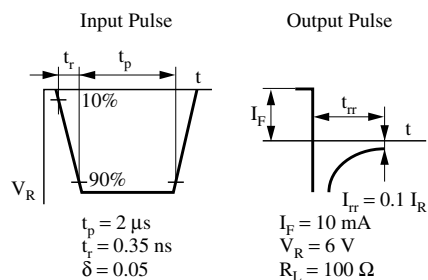
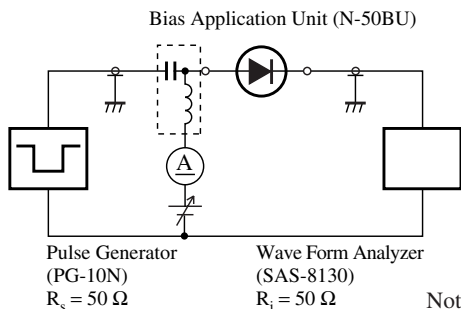
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. Absolute frequency of input and output is 100 MHz.

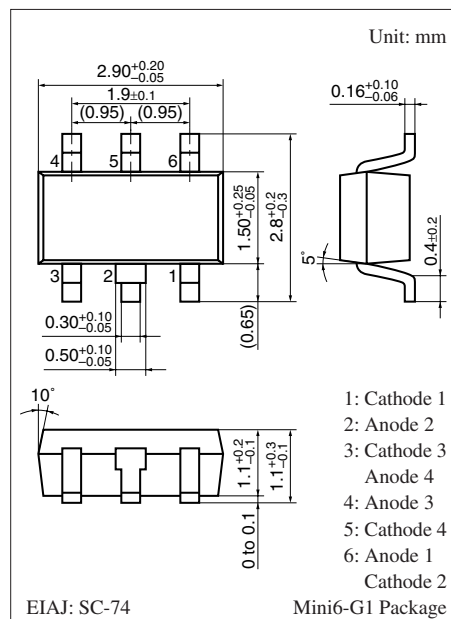
3. *1: Between pins 1 and 6, Between pins 3 and 5

*2: Between pins 2 and 6, Between pins 3 and 4

*3: t_{rr} measurement circuit

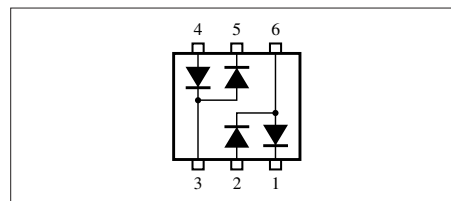


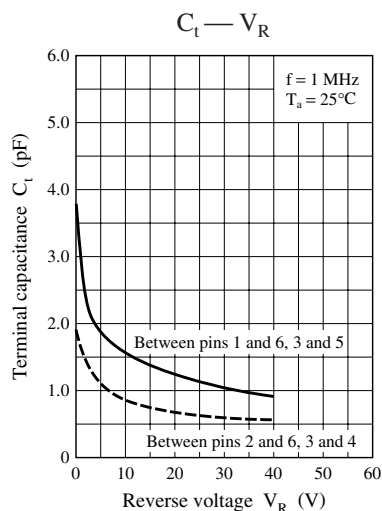
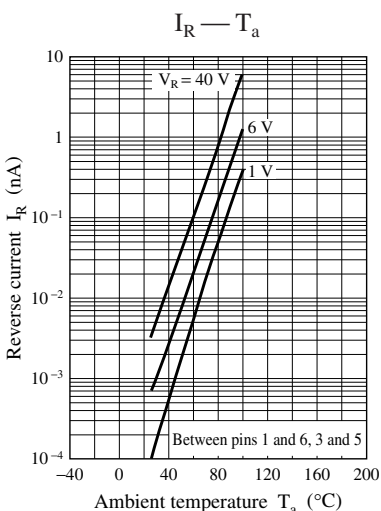
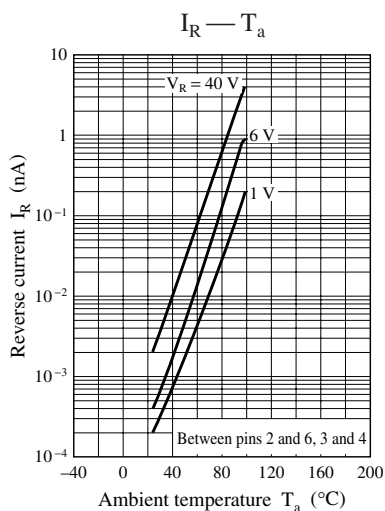
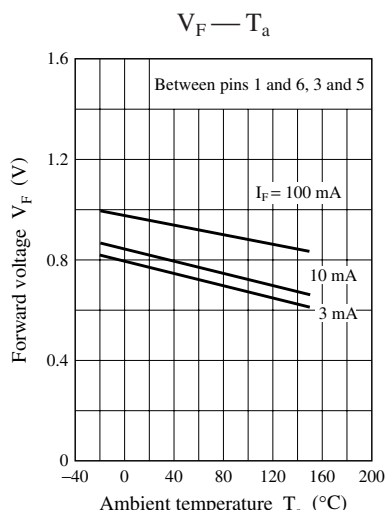
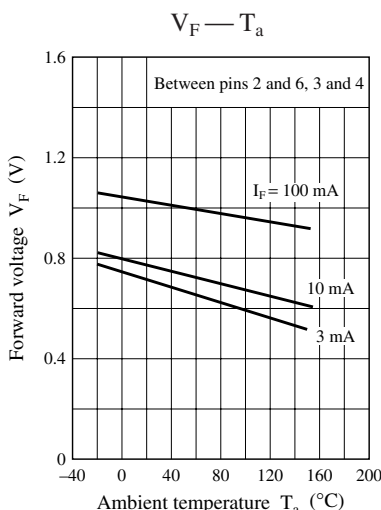
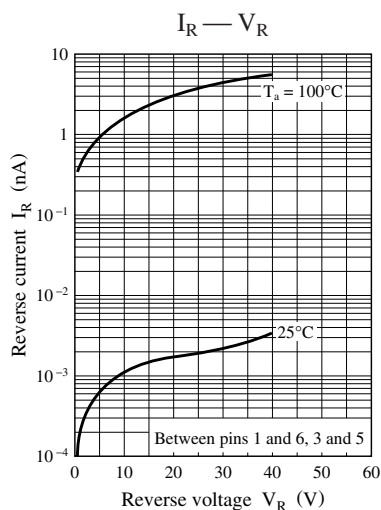
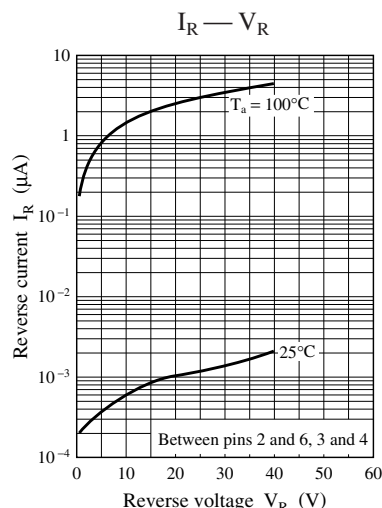
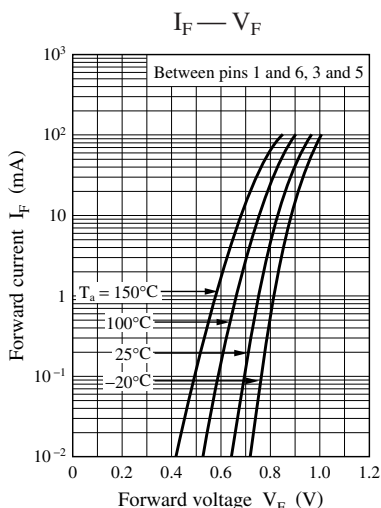
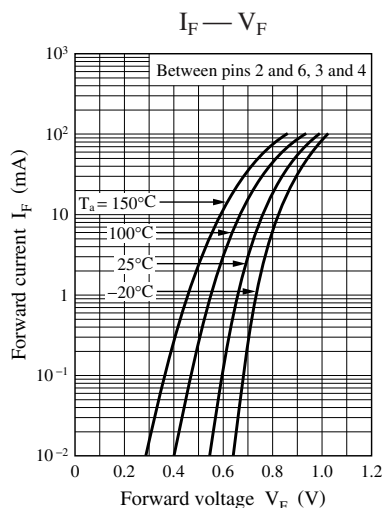
Note) The part number in the parenthesis shows conventional part number.

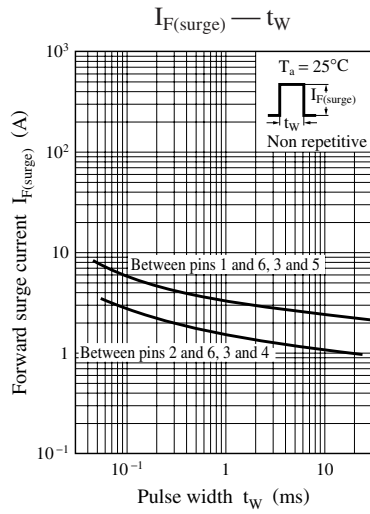


Marking Symbol: M2I

Internal Connection







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